



Material Content Data Sheet



Sales Product Name		2EDL05I06BF		Issued		19. July 2018		
MA#		MA001371650						
Package		PG-DSO-8-53		Weight*		80.26 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.952	1.19	1.19	11864	11864
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		105	
	non noble metal	zinc	7440-66-6	0.034	0.04		419	
	non noble metal	iron	7439-89-6	0.673	0.84		8387	
wire	non noble metal	copper	7440-50-8	27.330	34.05	34.94	340529	349440
	noble metal	gold	7440-57-5	0.185	0.23	0.23	2305	2305
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1237
encapsulation	plastics	epoxy resin	-	5.359	6.68		66771	
	inorganic material	silicondioxide	60676-86-0	44.162	55.02	61.82	550246	618254
leadfinish	non noble metal	tin	7440-31-5	0.824	1.03	1.03	10267	10267
plating	noble metal	silver	7440-22-4	0.090	0.11	0.11	1116	1116
glue	plastics	acrylic resin	-	0.119	0.15		1486	
	noble metal	silver	7440-22-4	0.423	0.53	0.68	5268	6754
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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